

## POWER SCHOTTKY RECTIFIER

### MAIN PRODUCTS CHARACTERISTICS

<b>I<sub>F(AV)</sub></b>	<b>2 x 7.5 A</b>
<b>V<sub>RRM</sub></b>	<b>60 V</b>
<b>T<sub>j (max)</sub></b>	<b>150 °C</b>
<b>V<sub>F (max)</sub></b>	<b>0.52 V</b>

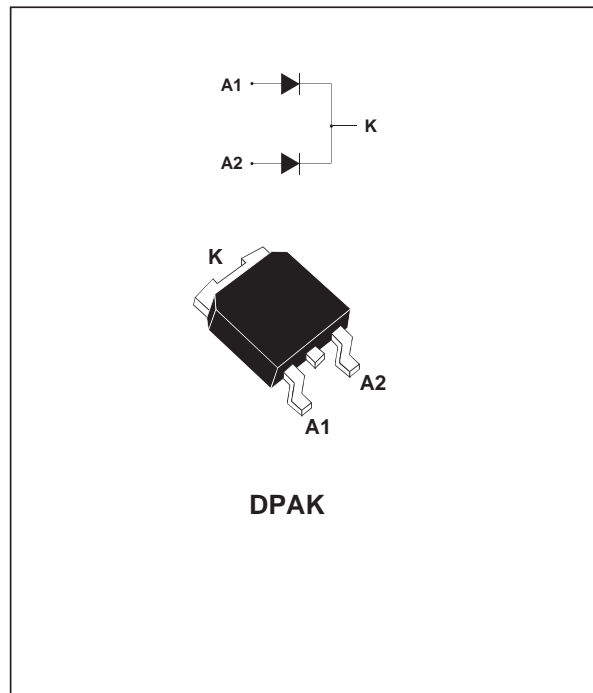
### FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP
- LOW THERMAL RESISTANCE
- AVALANCHE CAPABILITY SPECIFIED

### DESCRIPTION

Dual center tab Schottky rectifier suited for Switch Mode Power Supply and high frequency DC to DC converters.

Package in DPAK, this device is intended for use in low voltage, high frequency inverters, free-wheeling and polarity protection applications.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter		Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage		60	V	
I <sub>F(RMS)</sub>	RMS forward current		10	A	
I <sub>F(AV)</sub>	Average forward current	T <sub>c</sub> = 135°C	Per diode	7.5	A
		δ = 0.5	Per device	15	
I <sub>FSM</sub>	Surge non repetitive forward current	tp = 10 ms sinusoidal	75	A	
I <sub>RRM</sub>	Peak repetitive reverse current	tp=2 μs square F=1kHz	1	A	
P <sub>ARM</sub>	Repetitive peak avalanche power	tp = 1 μs T <sub>j</sub> = 25°C	3700	W	
T <sub>stg</sub>	Storage temperature range		- 65 to + 175	°C	
T <sub>j</sub>	Maximum operating junction temperature *		150	°C	
dV/dt	Critical rate of rise reverse voltage		10000	V/μs	

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  thermal runaway condition for a diode on its own heatsink

# STPS15L60CB

## THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	4	°C/W
		Total	2.4	
$R_{th(c)}$	Coupling		0.7	

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode } 1) = P(\text{diode } 1) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode } 2) \times R_{th(c)}$$

## STATIC ELECTRICAL CHARACTERISTICS (per diode)

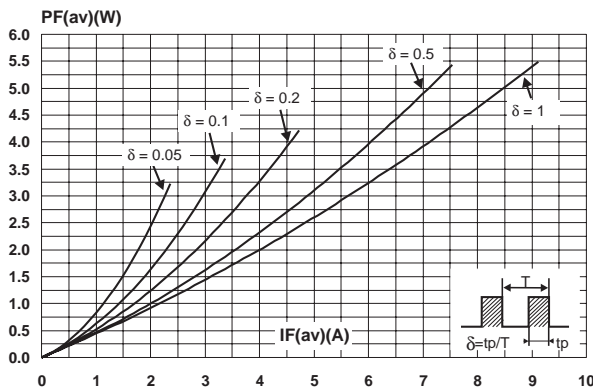
Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit		
$I_R^*$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			200	$\mu\text{A}$		
		$T_j = 125^\circ\text{C}$			45	60	mA		
$V_F^*$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 7.5 \text{ A}$			0.62	V		
		$T_j = 125^\circ\text{C}$			0.52	0.57			
		$T_j = 25^\circ\text{C}$		$I_F = 12 \text{ A}$				0.76	
		$T_j = 125^\circ\text{C}$				0.62		0.68	
		$T_j = 25^\circ\text{C}$			$I_F = 15 \text{ A}$				0.82
		$T_j = 125^\circ\text{C}$						0.66	0.72

Pulse test : \*  $t_p = 380 \mu\text{s}$ ,  $\delta < 2\%$

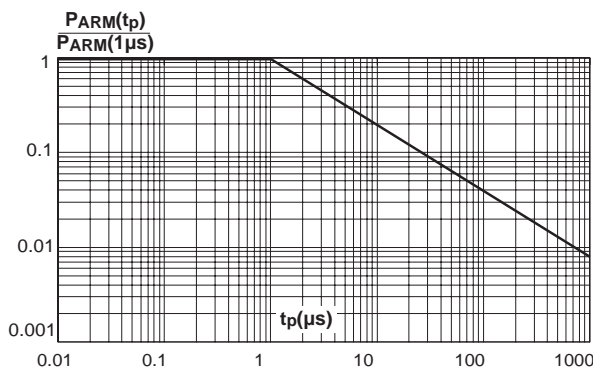
To evaluate the conduction losses use the following equation :

$$P = 0.32 \times I_{F(AV)} + 0.027 I_{F(RMS)}^2$$

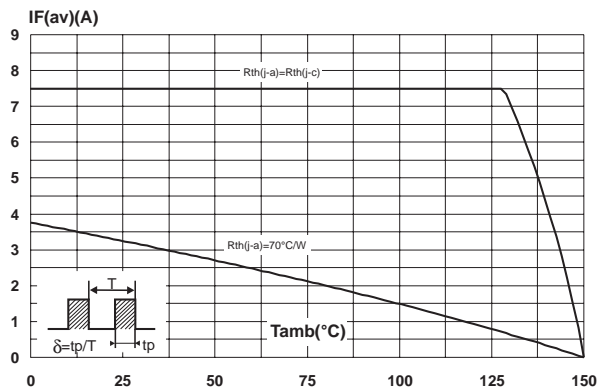
**Fig. 1:** Conduction losses versus average current.



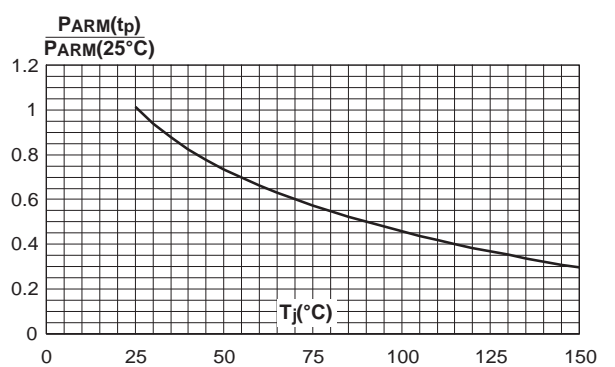
**Fig. 3:** Normalized avalanche power derating versus pulse duration.



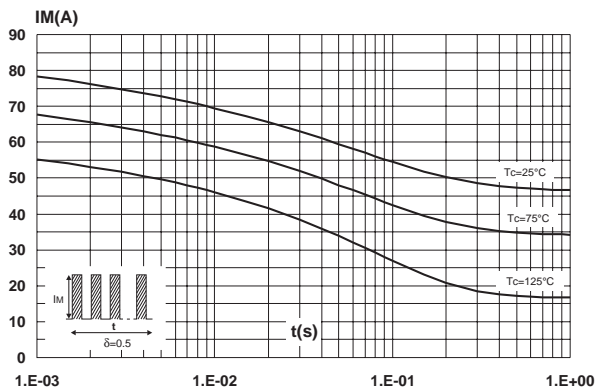
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ ).



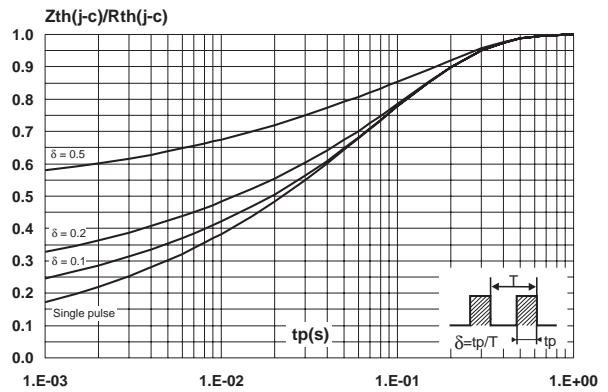
**Fig. 4:** Normalized avalanche power derating versus junction temperature.



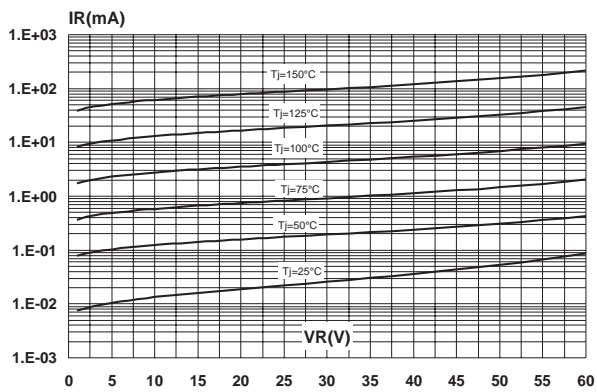
**Fig. 5:** Non repetitive surge peak forward current versus overload duration (maximum values).



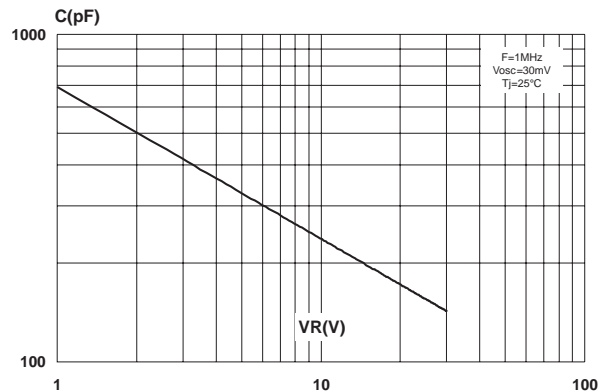
**Fig. 6:** Relative variation of thermal impedance junction to case versus pulse duration.



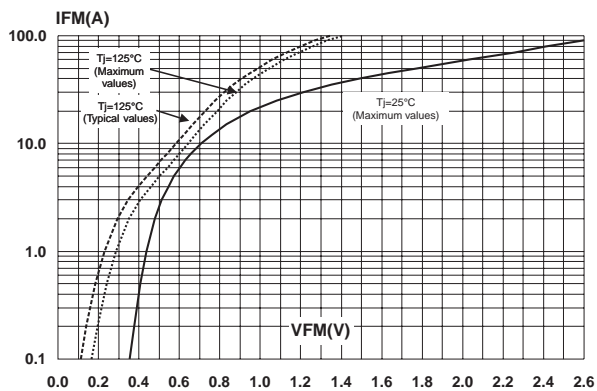
**Fig. 7:** Reverse leakage current versus reverse voltage applied (typical values).



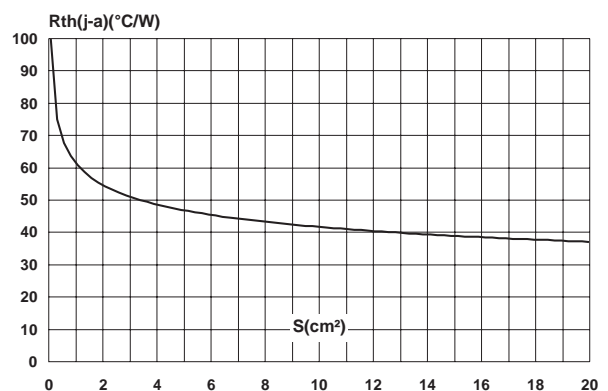
**Fig. 8:** Junction capacitance versus reverse voltage applied (typical values).



**Fig. 9:** Forward voltage drop versus forward current.

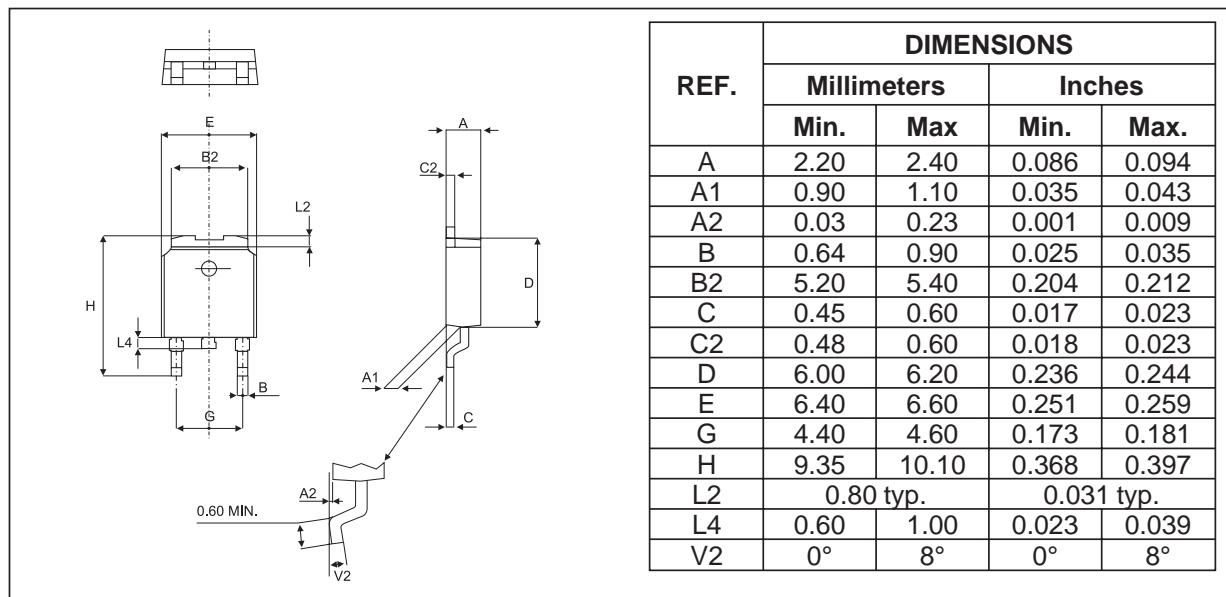


**Fig. 10:** Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, Cu = 35µm).

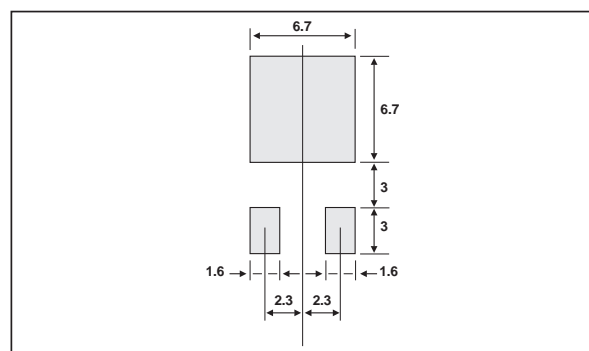


# STPS15L60CB

## PACKAGE MECHANICAL DATA DPAK



### FOOTPRINT (dimensions in mm)



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS15L60CB	S15L60C	DPAK	0.30 g	75	Tube
STPS15L60CB-TR	S15L60C	DPAK	0.30 g	2500	Tape & reel

#### ■ EPOXY MEETS UL94,V0

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